

# M54/74HC374 M54/74HC534

# OCTAL D-TYPE FLIP FLOP WITH 3 STATE OUTPUT HC374 NON INVERTING - HC534 INVERTING

- HIGH SPEED
  - $f_{MAX} = 77 \text{ MHz} (TYP.) \text{ AT } V_{CC} = 5 \text{ V}$
- LOW POWER DISSIPATION ICC = 4 µA (MAX.) AT T<sub>A</sub> = 25 °C
- HIGH NOISE IMMUNITY

  V<sub>NIH</sub> = V<sub>NIL</sub> = 28 % V<sub>CC</sub> (MIN)
- OUTPUT DRIVE CAPABILITY 15 LSTTL LOADS
- SYMMETRICAL OUTPUT IMPEDANCE IOL = IOH = 6 mA (MIN.)
- BALANCED PROPAGATION DELAYS
- WIDE OPERATING VOLTAGE RANGE V<sub>CC</sub> (OPR) = 2 V TO 6 V
- PIN AND FUNCTION COMPATIBLE WITH 54/74LS374/534

# B1R (Plastic Package) (Ceramic Package) M1R (Micro Package) (Chip Carrier) ORDER CODES: M54HCXXXF1R M74HCXXXM1R M74HCXXXB1R M74HCXXXC1R

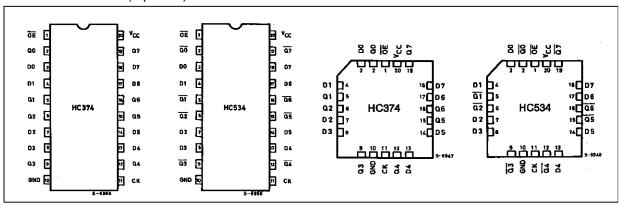
#### **DESCRIPTION**

The M54/74HC374, M54/74HC534, are high speed CMOS OCTAL D-TYPE FLIP FLOP WITH 3-STATE OUTPUTS fabricated with in silicon gate  $C^2$ MOS technology. They have the same high speed performance of LSTTL combined with true CMOS low power comsuption. These8-bit D-type flip-flops are controlled by a clock input (CK) and an ouput enable input  $(\overline{OE})$ . On the positive transition of the clock, the Q outputs will be set to the logic state that were setup at the D inputs (HC374) or their complements (HC534).

While the OE input is low, the eight outputs will be in a normal logic state (high or low logic level), and

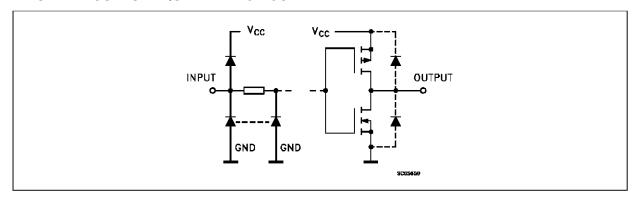
while high level, the outputs will be in a high impedance state. The output control does not affect the internal operation of flip-flops. That is, the old data can be retained or the new data can be entered even while the outputs are off. The application engineer has a choice of combination of inverting and non-inverting outputs. The HC374 and HC574 are identical, apart from pin layout. The 3-state output configuration and the wide choice of outline make bus-organized systems simple. All inputs are equipped with protection circuits against static discharge and transient excess voltage.

#### PIN CONNECTION (top view)



March 1993 1/13

#### INPUT AND OUTPUT EQUIVALENT CIRCUIT



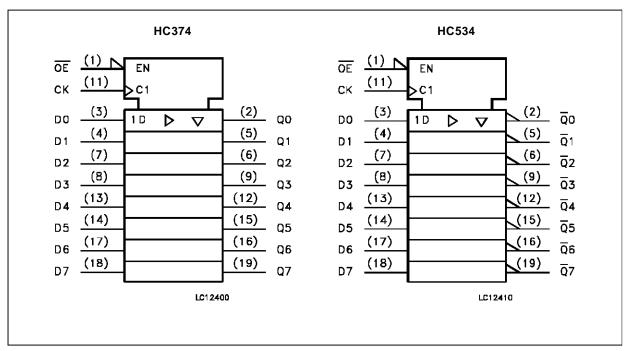
#### **PIN DESCRIPTION** (HC374)

PIN No	SYMBOL	NAME AND FUNCTION
1	OE	3 State output Enable Input (Active LOW)
2, 5, 6, 9, 12, 15, 16, 19	Q0 to Q7	3 State outputs
3, 4, 7, 8, 13, 14, 17, 18	D0 to D7	Data Inputs
11	CLOCK	Clock Input (LOW to HIGH, edge triggered)
10	GND	Ground (0V)
20	V <sub>CC</sub>	Positive Supply Voltage

#### PIN DESCRIPTION (HC534)

PIN No	SYMBOL	NAME AND FUNCTION
1	ŌĒ	3 State output Enable Input (Active LOW)
2, 5, 6, 9, 12, 15, 16, 19	Q0 to Q7	3 State outputs
3, 4, 7, 8, 13, 14, 17, 18	D0 to D7	Data Inputs
11	CLOCK	Clock Input (LOW to HIGH, edge triggered)
10	GND	Ground (0V)
20	V <sub>CC</sub>	Positive Supply Voltage

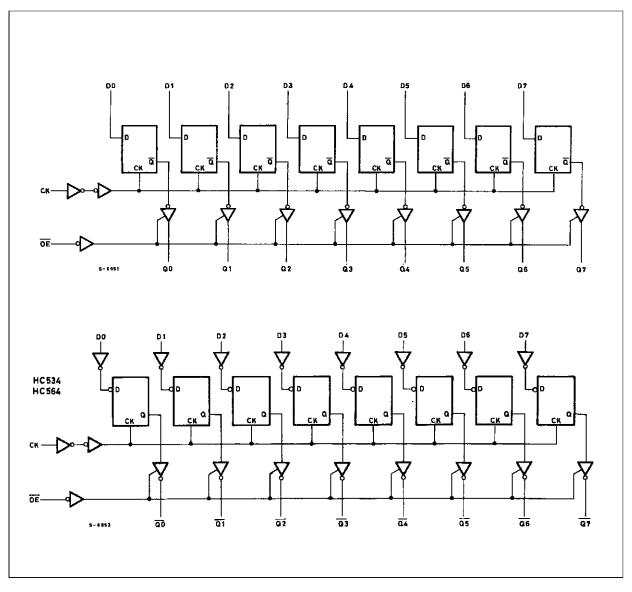
#### **IEC LOGIC SYMBOLS**



#### **TRUTH TABLE**

	INPUTS	OUTPUTS			
ŌĒ	СК	D	Q (HC374)	Q (HC534)	
Н	X	X	Z	Z	
L	l	X	NO CHANGE	NO CHANGE	
L		L	L	Н	
L		Н	Н	L	

#### **LOGIC DIAGRAMS**



#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
Vcc	Supply Voltage	-0.5 to +7	V
VI	DC Input Voltage	-0.5 to V <sub>CC</sub> + 0.5	V
Vo	DC Output Voltage	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	± 20	mA
lok	DC Output Diode Current	± 20	mA
lo	DC Output Source Sink Current Per Output Pin	± 35	mA
Icc or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current	± 70	mA
P <sub>D</sub>	Power Dissipation	500 (*)	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
TL	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these condition is not implied. (\*) 500 mW:  $\cong$  65 °C derate to 300 mW by 10mW/°C: 65 °C to 85 °C

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Value	Unit	
$V_{CC}$	Supply Voltage		2 to 6	V
$V_{I}$	Input Voltage		0 to V <sub>CC</sub>	V
Vo	Output Voltage		0 to V <sub>CC</sub>	V
$T_op$	Operating Temperature: M54HC Series M74HC Series		-55 to +125 -40 to +85	°C °C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	V <sub>CC</sub> = 2 V	0 to 1000	ns
		V <sub>CC</sub> = 4.5 V	0 to 500	
		V <sub>CC</sub> = 6 V	0 to 400	

#### **DC SPECIFICATIONS**

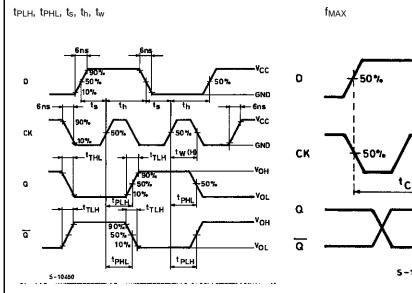
		Test Conditions			Value							
Symbol	Parameter	Vcc				$T_A = 25$ °C 54HC and 74HC		-40 to 85 °C 74HC		-55 to 125 °C 54HC		Unit
		(V)			Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
$V_{IH}$	High Level Input	2.0			1.5			1.5		1.5		
	Voltage	4.5			3.15			3.15		3.15		V
		6.0			4.2			4.2		4.2		
$V_{IL}$	Low Level Input	2.0					0.5		0.5		0.5	
	Voltage	4.5					1.35		1.35		1.35	V
		6.0					1.8		1.8		1.8	
$V_{OH}$	High Level	2.0	V <sub>I</sub> =		1.9	2.0		1.9		1.9		
	Output Voltage	4.5	VIH	I <sub>O</sub> =-20 μA	4.4	4.5		4.4		4.4		
		6.0	or		5.9	6.0		5.9		5.9		_ V
		4.5	V <sub>IL</sub>	I <sub>O</sub> =-6.0 mA	4.18	4.31		4.13		4.10		
		6.0		I <sub>O</sub> =-7.8 mA	5.68	5.8		5.63		5.60		
$V_{OL}$	Low Level Output	2.0	V <sub>I</sub> =			0.0	0.1		0.1		0.1	
	Voltage	4.5	V <sub>IH</sub>	I <sub>O</sub> = 20 μA		0.0	0.1		0.1		0.1	\ /
		6.0	or			0.0	0.1		0.1		0.1	V
		4.5	VIL	I <sub>O</sub> = 6.0 mA		0.17	0.26		0.33		0.40	
		6.0		I <sub>O</sub> = 7.8 mA		0.18	0.26		0.33		0.40	
lı	Input Leakage Current	6.0	Vı = '	V <sub>I</sub> = V <sub>CC</sub> or GND			±0.1		±1		±1	μΑ
I <sub>OZ</sub>	3 State Output Off State Current	6.0		V <sub>IH</sub> or V <sub>IL</sub>			±0.5		±5.0		±10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	6.0		V <sub>CC</sub> or GND			4		40		80	μΑ

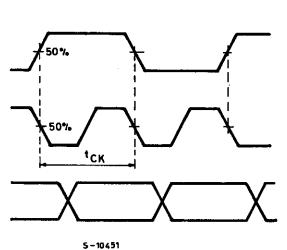
## AC ELECTRICAL CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , Input $t_f = t_f = 6 \text{ ns}$ )

		Te	est Co	nditions				Value				
Symbol	Parameter	Vcc	C <sub>L</sub>			<sub>A</sub> = 25 <sup>o</sup> C and 7			85 °C HC		125 °C HC	Unit
		(V)	(pF)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
t <sub>TLH</sub>	Output Transition	2.0				25	60		75		90	
t <sub>THL</sub>	Time	4.5	50			7	12		15		18	ns
		6.0				6	10		13		15	
t <sub>PLH</sub>	Propagation	2.0				45	140		175		210	
t <sub>PHL</sub>	Delay Time	4.5	50			15	28		35		42	ns
	$(CLOCK - Q, \overline{Q})$	6.0				13	24		30		36	
		2.0				60	190		240		285	
		4.5	150			20	38		48		57	ns
		6.0				17	32		41		48	
t <sub>PLZ</sub>	3 State Output	2.0				39	135		170		205	
t <sub>PHZ</sub>	Enable Time	4.5	50	$R_L = 1 K\Omega$		13	27		34		41	ns
		6.0				11	23		29		35	
		2.0				54	185		230		280	
		4.5	150	$R_L = 1 K\Omega$		18	37		46		56	ns
		6.0				15	31		39		48	
f <sub>MAX</sub>	Maximum CLock	2.0			6.2	18		5		4.2		
	Frequency	4.5	50		31	75		25		21		ns
		6.0			37	90		30		25		
t <sub>W(L)</sub>	Minimum Pulse	2.0				15	75		95		110	
t <sub>W(H)</sub>	Width (CLOCK)	4.5	50			6	15		19		22	ns
		6.0				6	13		16		19	
ts	Minimum Set-up	2.0				25	75		95		110	
	Time	4.5	50			6	15		19		22	ns
		6.0				4	13		16		19	
t <sub>h</sub>	Minimum Hold	2.0					0		0		0	
	Time	4.5	50				0		0		0	ns
		6.0					0		0		0	
C <sub>IN</sub>	Input Capacitance					5	10		10		10	pF
Соит	Out put Capacitance					10						pF
C <sub>PD</sub> (*)	Power Dissipation Capacitance					47						pF

<sup>(\*)</sup> C<sub>PD</sub> is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operting current can be obtained by the following equation. I<sub>CC</sub>(opr) = C<sub>PD</sub> •V<sub>CC</sub> •f<sub>IN</sub> + I<sub>CC</sub>/8 (per FLIP-FLOP) and C<sub>PD</sub> when N pcs of FLIP-FLOP operate, can be gained by following equation: C<sub>PD</sub> (TOTAL) = 30 + 17 x N (pF)

#### SWITCHING CHARACTERISTICS TEST WAVEFORM





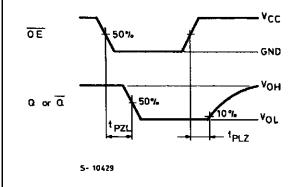
tplz, tpzl

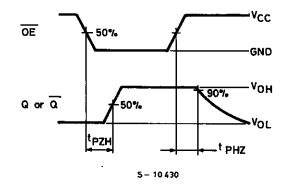
The 1K $\Omega$  load resistors should be connected between outputs and V $_{CC}$  line and the 50pF load capacitors should be connected between outputsand GND line. All inputs except  $\overline{OE}$  input should be connected to V $_{CC}$  line or GND line such that outputs will be in low logic level while  $\overline{OE}$  input is held low.

t<sub>PHZ</sub>, t<sub>PZH</sub>

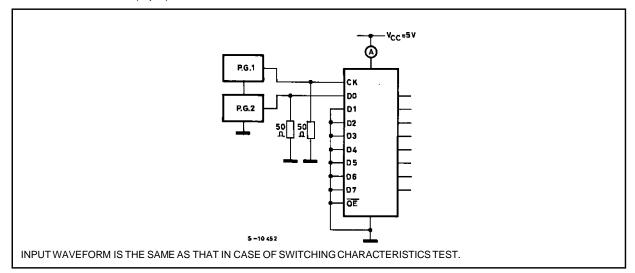
The 1K $\!\Omega$  load resistors and the 50pF load capacitors should be connected between each output and GND line.

All inputs except  $\overline{\text{OE}}$  input should be connected to  $V_{\text{CC}}$  or  $\overline{\text{GND}}$  line such that output will be in high logic level while  $\overline{\text{OE}}$  input is held low.



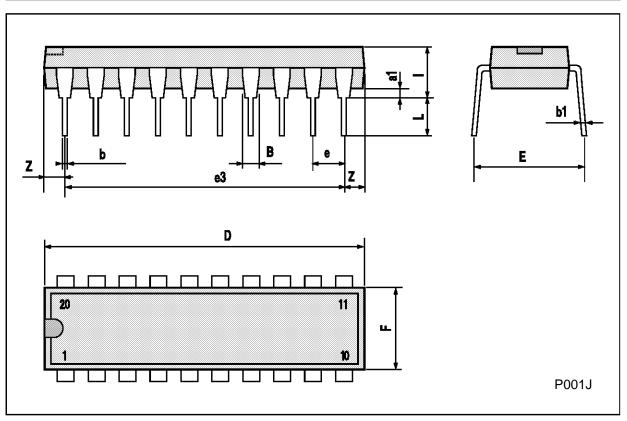


## TEST CIRCUIT Icc (Opr.)



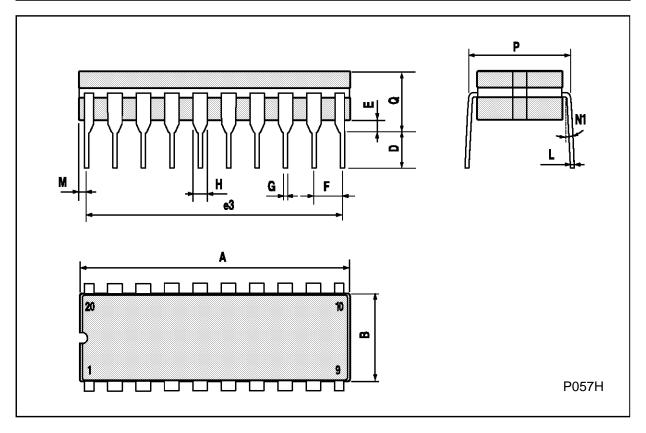
# Plastic DIP20 (0.25) MECHANICAL DATA

DIM.		mm				
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
a1	0.254			0.010		
В	1.39		1.65	0.055		0.065
b		0.45			0.018	
b1		0.25			0.010	
D			25.4			1.000
E		8.5			0.335	
е		2.54			0.100	
e3		22.86			0.900	
F			7.1			0.280
I			3.93			0.155
L		3.3			0.130	
Z			1.34			0.053



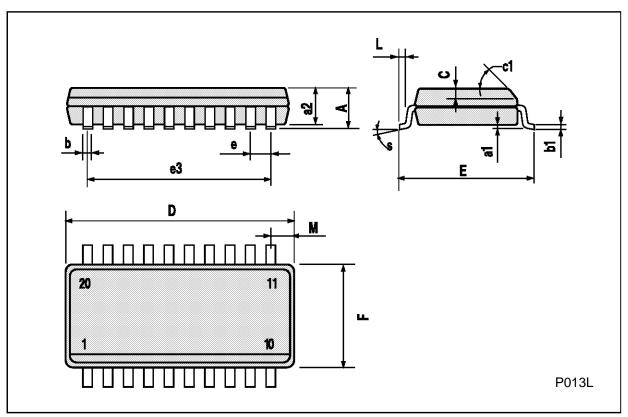
# **Ceramic DIP20 MECHANICAL DATA**

DIM.		mm			inch	
Diwi.	MIN.	TYP. MAX.		MIN.	TYP.	MAX.
А			25			0.984
В			7.8			0.307
D		3.3			0.130	
E	0.5		1.78	0.020		0.070
e3		22.86			0.900	
F	2.29		2.79	0.090		0.110
G	0.4		0.55	0.016		0.022
Ι	1.27		1.52	0.050		0.060
L	0.22		0.31	0.009		0.012
М	0.51		1.27	0.020		0.050
N1			4° (min.),	15° (max.)		
Р	7.9		8.13	0.311		0.320
Q			5.71			0.225



# **SO20 MECHANICAL DATA**

DIM.		mm			inch	
Dilvi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			2.65			0.104
a1	0.10		0.20	0.004		0.007
a2			2.45			0.096
b	0.35		0.49	0.013		0.019
b1	0.23		0.32	0.009		0.012
С		0.50			0.020	
c1			45°	(typ.)		
D	12.60		13.00	0.496		0.512
E	10.00		10.65	0.393		0.419
е		1.27			0.050	
e3		11.43			0.450	
F	7.40		7.60	0.291		0.299
L	0.50		1.27	0.19		0.050
М			0.75			0.029
S			8° (r	nax.)		



# **PLCC20 MECHANICAL DATA**

DIM.		mm		inch			
Diwi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	9.78		10.03	0.385		0.395	
В	8.89		9.04	0.350		0.356	
D	4.2		4.57	0.165		0.180	
d1		2.54			0.100		
d2		0.56			0.022		
E	7.37		8.38	0.290		0.330	
е		1.27			0.050		
e3		5.08			0.200		
F		0.38			0.015		
G			0.101			0.004	
М		1.27			0.050		
M1		1.14			0.045		



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